

Surface Mount Ultrafast Rectifier

ES1DAF, ES1JAF

Features

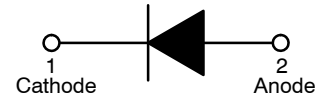
- Fast Switching Speed – Maximum T_{rr} 35 ns
- Ultra Thin Profile – Maximum Height of 1.0 mm
- Glass Passivated Junction
- UL Flammability 94V-0 Classification
- MSL 1
- Green Mold Compound
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

Specifications

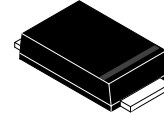
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value		Unit
		ES1DAF	ES1JAF	
V_{RRM}	Recurrent Peak Reverse Voltage	200	600	V
V_{RMS}	RMS Voltage	140	420	V
V_R	DC Blocking Voltage	200	600	V
$I_{F(AV)}$	Average Forward Current	1		A
I_{FSM}	Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed on Rated Load	30		A
T_J	Operating Junction Temperature Range	-55 to +150		$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150		$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



Ultrafast Rectifier



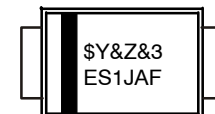
DO-214AD
(SMAF)
CASE 403AD

MARKING DIAGRAMS



Band Indicates Cathode

\$Y = onsemi Logo
 &Z = Assembly Plant Code
 &3 = Data Code (Year & Week)
 ES1DAF = Specific Device Code



Band Indicates Cathode

\$Y = onsemi Logo
 &Z = Assembly Plant Code
 &3 = Data Code (Year & Week)
 ES1JAF = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ES1DAF, ES1JAF

THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Value	Unit
Ψ_{JL}	Typical Thermal Characteristics, Junction-to-Lead (Note 1)	24	$^\circ\text{C/W}$
$R_{\theta JA}$	Typical Thermal Resistance, Junction-to-Ambient (Note 2)	150	$^\circ\text{C/W}$

1. Mounted on an FR4 PCB, single-sided copper, with 48 cm² copper pad area.
2. Mounted on an FR4 PCB, single-sided copper, mini pad.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	Forward Voltage	$I_F = 1\text{ A}$				
		ES1DAF	–	–	0.95	V
		ES1JAF	–	–	1.70	
I_R	Reverse Current	$V_R = V_{DC}$	–	–	1	μA
t_{rr}	Reverse Recovery Time	$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	–	–	34	ns
C_J	Junction Capacitance	$V_R = 4\text{ V}$, $f = 1\text{ MHz}$	–	15	–	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping [†]
ES1DAF	ES1DAF	DO-214AD (SMAF) (Pb-Free/Halogen Free)	10000 / Tape & Reel
ES1JAF	ES1JAF	DO-214AD (SMAF) (Pb-Free/Halogen Free)	10000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL PERFORMANCE CHARACTERISTICS

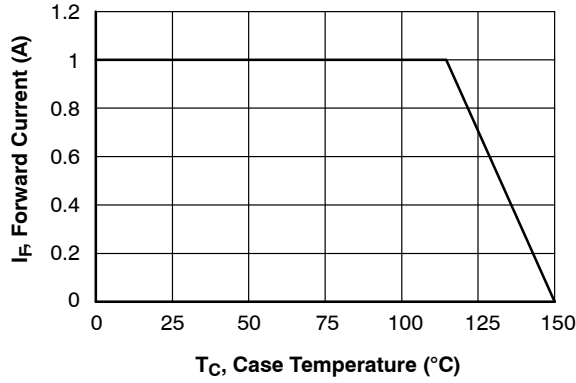


Figure 1. Forward Current Derating Curve

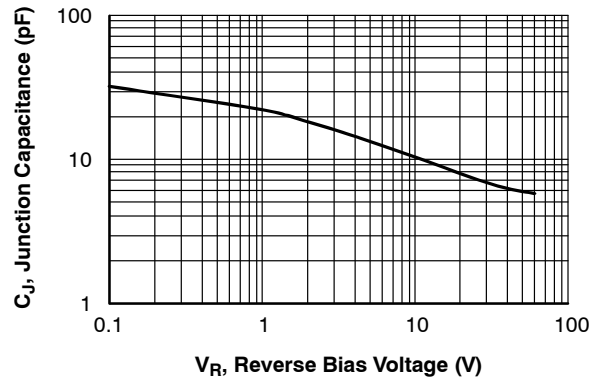


Figure 2. Typical Junction Capacitance

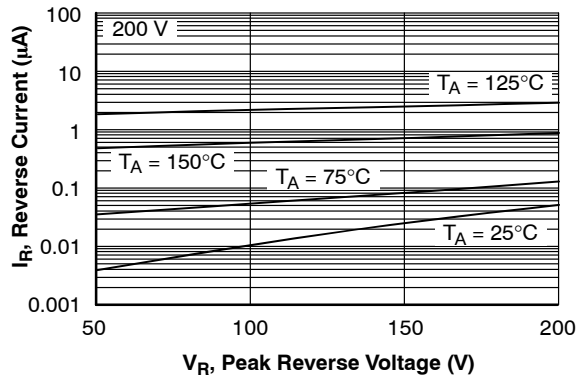


Figure 3. Typical Reverse Characteristics

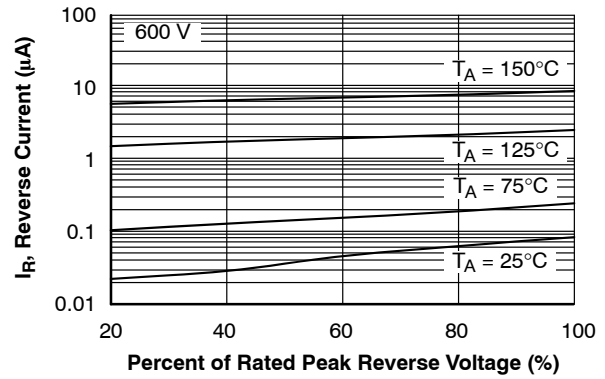


Figure 4. Typical Reverse Characteristics

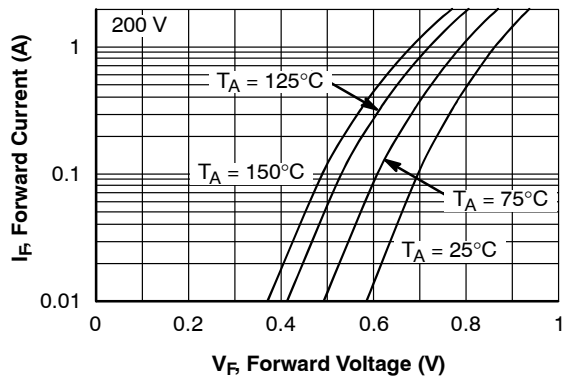


Figure 5. Typical Forward Characteristics

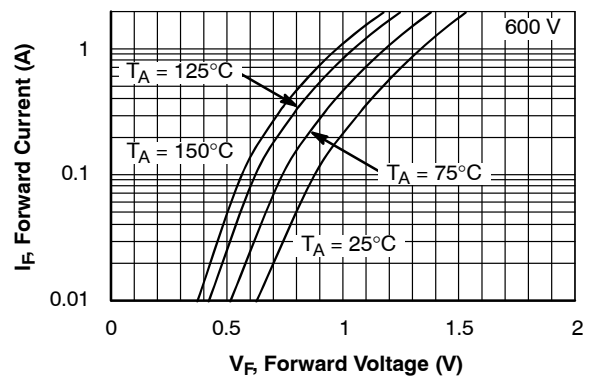
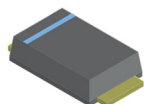
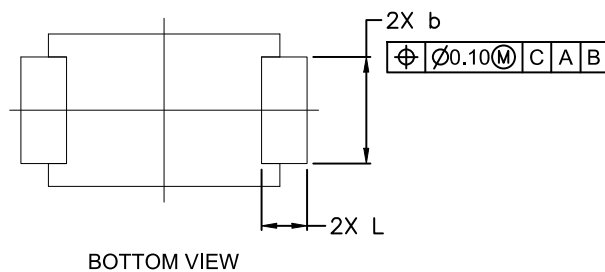
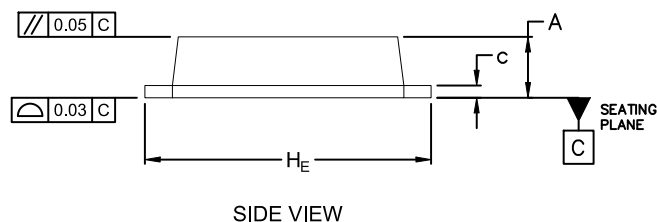
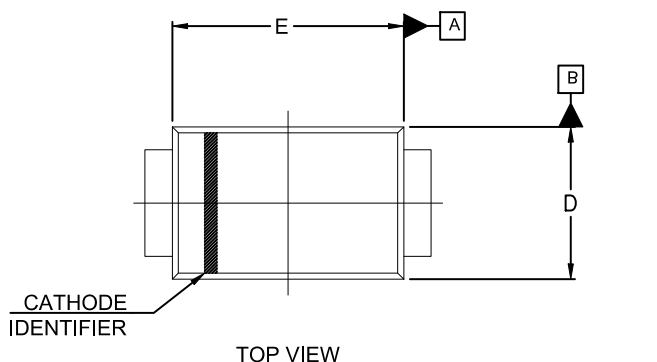


Figure 6. Typical Forward Characteristics


SMA-FL
CASE 403AD
ISSUE A

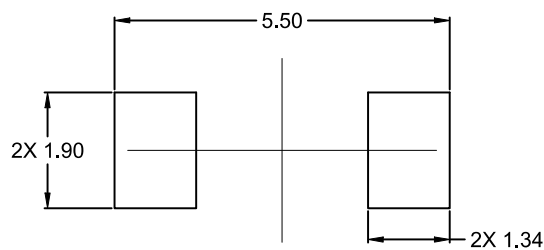
DATE 14 JUL 2020



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	1.25	1.60	1.90
c	0.10	—	0.25
D	2.30	2.50	2.70
E	3.60	3.95	4.30
H _E	4.40	4.80	5.20
L	0.50	0.75	0.95


RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON13439G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SMA-FL	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales